HAPTICS
INDUSTRY FORUM

Request for Proposal (RFP): Haptic Development Kit
09/09/2025

1. Introduction

This Request for Proposal (RFP) invites vendors to submit proposals for the development and delivery of a Haptic Development Kit for Haptic Industry Forum (HIF) members. The purpose of this RFP is to identify a partner capable of providing a kit which meets the requirements.

2. Project Overview

The Haptic Development Kit is intended to support research and development for HIF members to develop tactile feedback systems. The kit should be modular, scalable, and easy to use with various platforms like USB, Bluetooth, Wi-Fi.

3. Scope of Work

The selected vendor will be responsible for developing, testing, and delivering the Haptic Development Kit. This includes hardware components, software interfaces, documentation, and support services.

A total of 25 kits to be purchased by HIF from Nov 2025 to Feb 2026 timeframe.

4. Technical Requirements

The kit must meet the following technical specifications:

1. Include 1 LRA with operating voltage up to 2.1 Vrms, resonant frequency within 150-220 Hz with at least 2 Gpp output at resonant frequency and thickness not to exceed 3 mm, 1 voice coil with operating voltage from 0.3 to 1.2 Vrms, resonant frequency within 120-150 Hz with at least 2 Gpp at resonant frequency, 1 ERM with operating voltage 2-4.5 Vdc with min 2 Gpp at resonant frequency, 1 LMR actuator with resonant frequency 130 Hz and 4.5 Gpp output at resonant frequency
2. Support at least 2 channel simultaneous output for running 2 actuators simultaneouly
3. Compatibility with Windows and Mac
4. Support USB-C or Micro USB port on the board, Bluetooth Low energy 4.0 or above, Wi-Fi 4 or above connectivity
5. Support external integration for additional sensor like touch sensor through I2C or SPI or GPIO

6. Include GUI based software to adjust frequency, duration, intensity of input waveform without subscription
7. Compact driver board not to exceed 100 x 80 x 25 mm
8. Provide warranty of 3 months for hardware defects
9. Provide software with a non restrictive perpetual license without any royalty fees.

5. Proposal Submission Guidelines

Proposals must be submitted electronically in PDF format to the email address in Section 9. Each proposal must include company background, relevant experience, specification sheet for driver board, timeline for kit readiness, support services for troubleshooting and detailed cost including shipping.

6. Evaluation Criteria

Proposals will be evaluated based on the following criteria:

- Ability to meet technical requirements
- Cost-effectiveness
- Vendor experience and qualifications
- Support and maintenance offerings

7. Timeline

The following timeline applies to this RFP:

- RFP Release Date: 09/22/2025
- Proposal Submission Deadline: 10/21/2025
- Vendor Selection Date: 10/22/2025
- First deliveries to HIF members: From 12/01/2025 onwards

8. Budget and Payment terms

Cost for Dev Kit with shipping not to exceed USD200 per kit. If costs exceed this number, provide alternatives and options to defeature and lower the cost.

Once selected HIF will purchase the first 20 kits by 12/01/2025 with payment through Bank transfer/ACH and the remaining 5 kits by 01/31/2026.

9. Contact Information

For any questions or clarifications regarding this RFP, please contact:

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